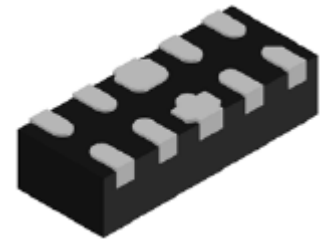




FEATURES

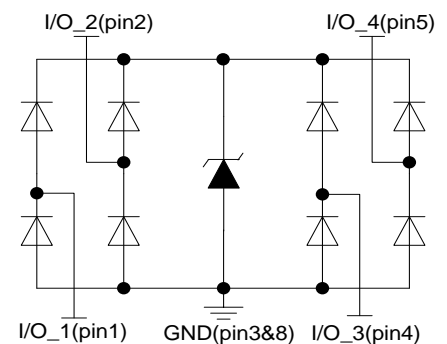
- ✧ Solid-state silicon-avalanche technology
- ✧ Up to four I/O lines of protection
- ✧ Low operating voltage: 5V
- ✧ Ultra low capacitance: 0.25pF typical(I/O to I/O)
- ✧ Low operating and clamping voltage
- ✧ Low leakage current
- ✧ RoHS compliant



DFN2510-10L

MAIN APPLICATIONS

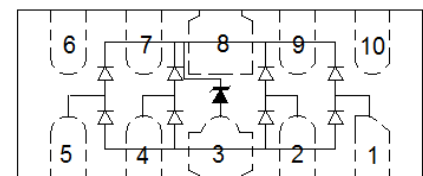
- ✧ Digital visual interface(DVI)
- ✧ Display port TM interface
- ✧ MDDI ports
- ✧ PCI express
- ✧ SATA interfaces
- ✧ High definition multi-media interface(HDMI)



Pin configuration

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) $\pm 20\text{kV}$ (air), $\pm 17\text{kV}$ (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 4A (8/20 μs)



Top view

MECHANICAL CHARACTERISTICS

- ✧ DFN2510-10L package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Quantity per reel: 3,000pcs
- ✧ Lead finish: lead free
- ✧ Marking code: 0524P

ABSOLUTE MAXIMUM RATINGS (T_A=25°C, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P _{PP}	100	W
ESD per IEC 61000-4-2 (Air)	V _{ESD}	+/- 20	kV
ESD per IEC 61000-4-2 (Contact)		+/- 17	
Lead soldering temperature	T _L	260 (10 sec.)	°C
Operating junction temperature range	T _J	-55 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V _{RWM}	I/O to GND			5.0	V
Reverse breakdown voltage	V _{BR}	I/O to GND@ I _T =1mA	6.0		8.5	V
Reverse leakage current	I _R	I/O to GND @V _{RWM} =5V			0.5	μA
Clamping voltage	V _C	I _{PP} =1A, t _p =8/20μs		9.5	10.5	V
		I _{PP} =4A, t _p =8/20μs		11	13	V
Junction capacitance	C _J	V _{RWM} =0V, f=1MHz I/O pin to GND		0.5	0.65	pF
		V _{RWM} =0V, f=1MHz Between I/O pins		0.25	0.35	pF

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25°C, unless otherwise noted)

FIG.1: V- I curve characteristics (Uni-directional)

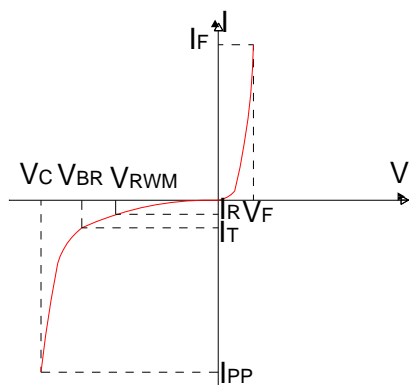


FIG.2: Pulse waveform (8/20μs)

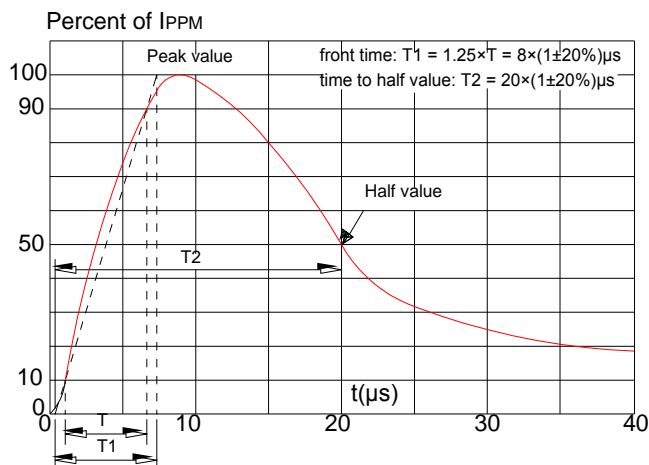


FIG.3: Pulse derating curve

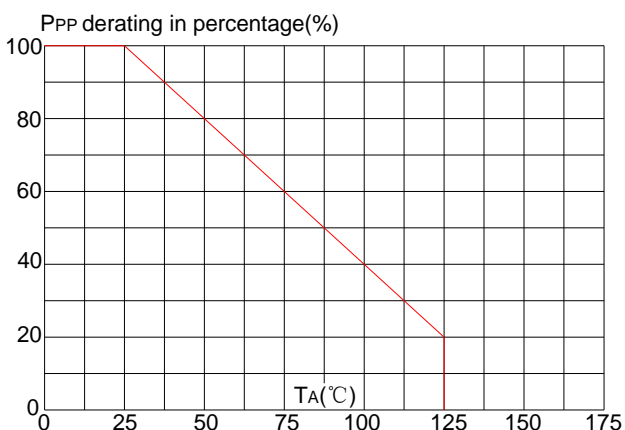
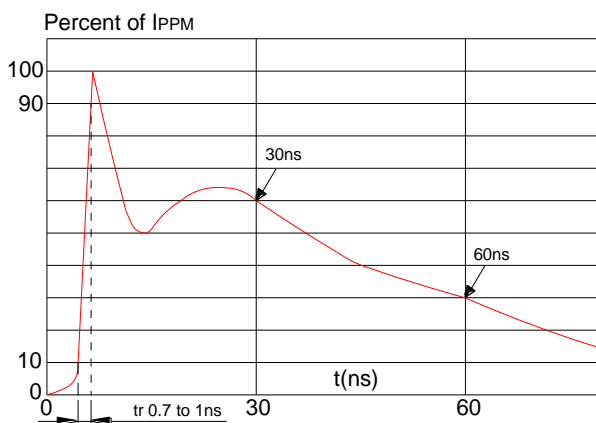
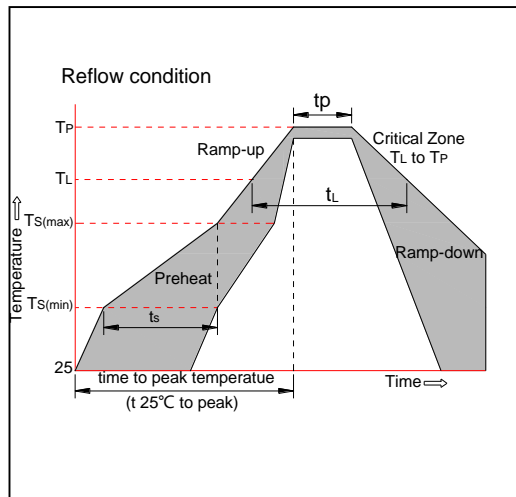


FIG.4: ESD clamping (20kV contact)

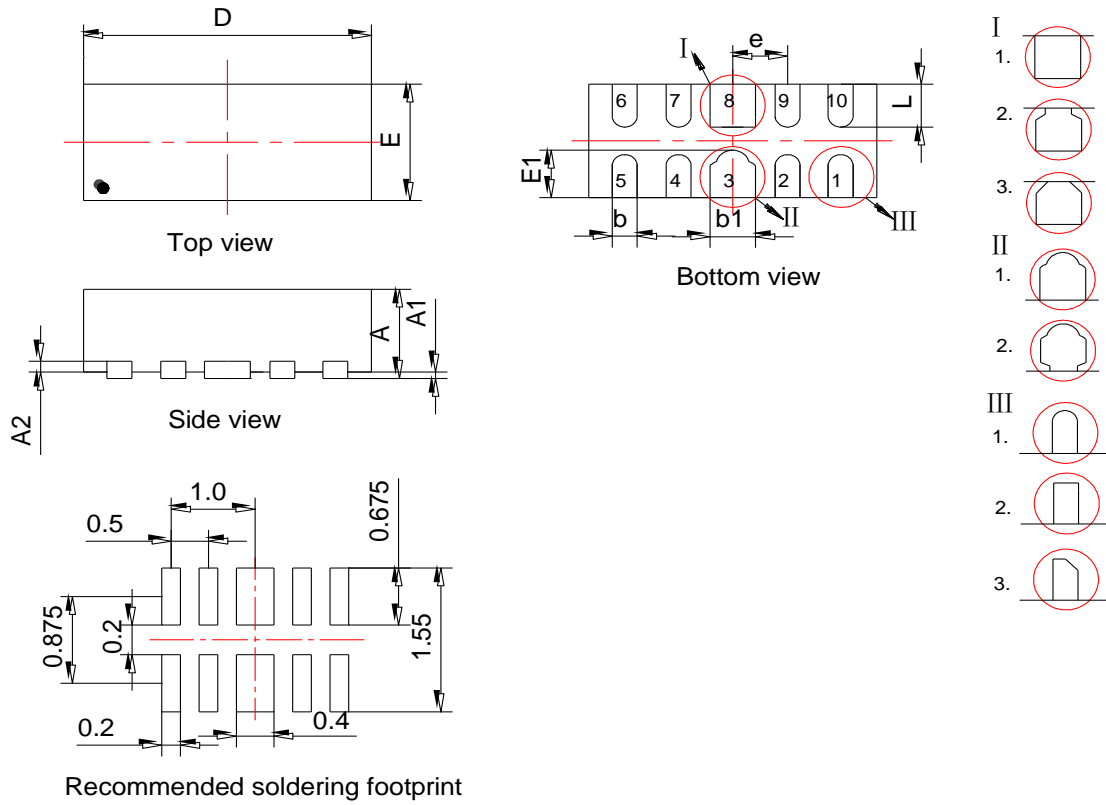


SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

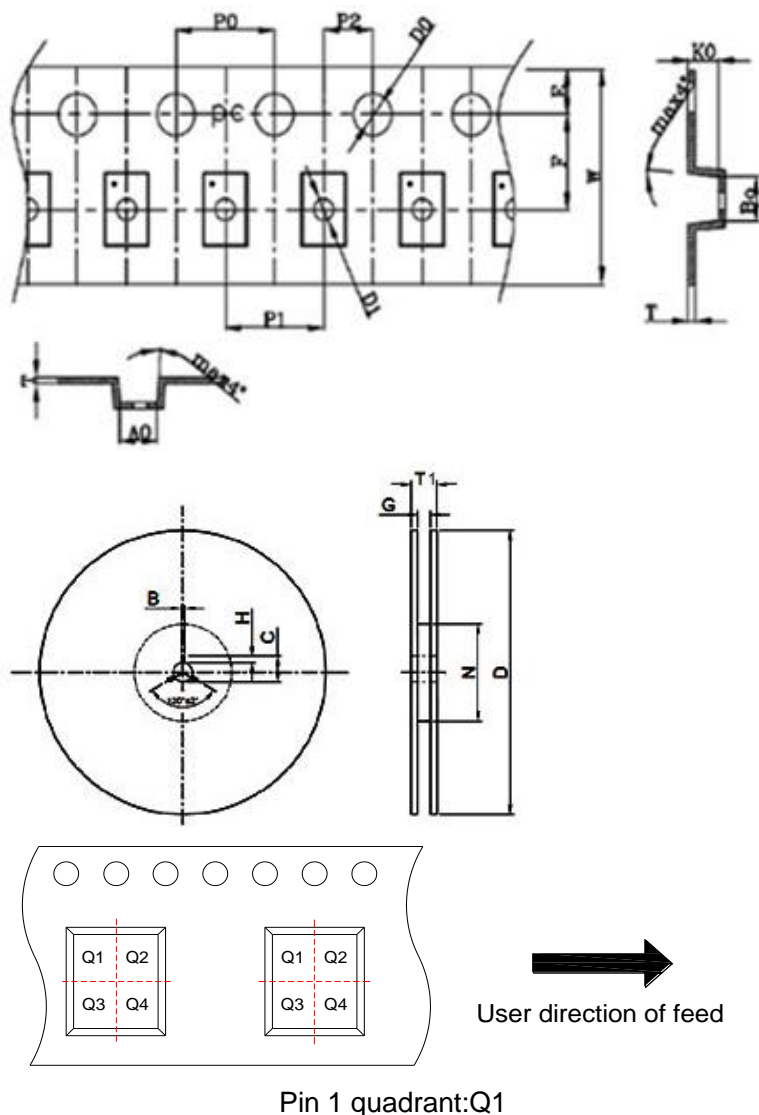


PACKAGE MECHANICAL DATA



Symbol	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.46	0.53	0.60	0.018	0.021	0.024
A1	0.00	0.02	0.05	0.000	0.001	0.002
A2	0.15Ref.			0.006Ref.		
b	0.15	0.20	0.25	0.006	0.008	0.010
b1	0.35	0.40	0.45	0.014	0.016	0.018
D	2.40	2.50	2.60	0.094	0.098	0.102
E	0.90	1.00	1.10	0.035	0.039	0.043
E1	0.30	0.40	0.56	0.012	0.016	0.022
e	0.50BSC			0.020BSC		
L	0.30	0.40	0.45	0.012	0.016	0.018

TAPE AND REEL INFORMATION-DFN2510-10L

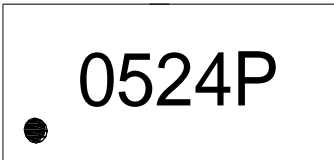


Symbol	Dimensions	
	Millimeters	Inches
	Typ.	Typ.
A0	1.20	0.047
B0	2.75	0.108
K0	0.70	0.028
P0	4.00	0.157
P1	4.00	0.157
P2	2.00	0.079
T	0.20	0.008
E	1.75	0.069
F	3.50	0.138
D0	1.55	0.061
D1	0.60	0.024
W	8.0	0.315
B	2.0	0.079
H	4.0	0.157
C	13.0	0.512
G	8.4	0.331
T1	14.9(max)	0.587(max)
N	60.0	2.362
D	178.0	7.000

ORDERING INFORMATION

Part Number	Package	Quantity Per Reel (PCS)	Reel Size
JEU0524PA	DFN2510-10L	3,000	7 Inch

MARKING CODE

Part Number	Marking Code
JEU0524PA	

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